



Summit Interconnect Announces Key Executive Appointments: Sean Patterson Named Chief Technology Officer, Michael Norman Joins as President and Chief Operating Officer

March 6, Irvine, CA – Summit Interconnect, a leading provider of advanced PCB manufacturing solutions, is pleased to announce two key leadership updates to its executive team.

First, Summit Interconnect has strategically expanded its leadership by creating the role of Chief Technology Officer (CTO). This key position will be filled by Sean Patterson, the current Chief Operating Officer. As CTO, Patterson will lead Summit's forward-looking technology vision, ensuring alignment with corporate goals and keeping the organization at the forefront of industry trends. He will oversee research and development, implement emerging technologies, and improve technical operations to make processes more efficient and cost-effective. His focus will also include using the latest technology advancements to enhance product quality and improve the customer experience.

Sean Patterson's experience leading operations at Summit Interconnect, Nano Dimension, and Amazon makes him well-suited for the role of Chief Technology Officer. "As the pace of innovation accelerates, leadership in emerging technologies such as artificial intelligence and the Internet of Things will be critical to maintaining a competitive edge," said Shane Whiteside, CEO of Summit Interconnect. "With Sean leading our technology initiatives as CTO, Summit will be well positioned for sustained success in an increasingly digital and interconnected world."



Sean Patterson



Michael Norman

Second, Summit is pleased to welcome Michael Norman to the team as its new President and Chief Operating Officer. With over 30 years of leadership experience in aerospace, defense, and technology, Norman brings a strong track record of managing complex operations and delivering high-performance solutions.

Norman joins Summit from Raytheon, where he served as Vice President of Space, Imaging, and Microelectronics, overseeing multiple subsidiaries focused on focal plane arrays/imagers, high-reliability electronics for satellite systems, and advanced semiconductor microelectronics. His prior leadership roles at L3Harris and Lockheed Martin further highlight his ability to successfully lead large-scale programs, improve operational efficiencies, and expand market reach.

"I am excited to join Summit and strengthen its leadership in the PCB industry at a critical time for U.S. manufacturing," said



Michael Norman, President and COO. "Summit's commitment to high-reliability circuit boards for aerospace, defense, and commercial industries is impressive. I look forward to working with this talented team to meet our customers' evolving technology needs."

Norman will oversee all North American operations, sales, and marketing to drive strategic growth and operational excellence across the organization. Shane Whiteside will continue to lead Summit Interconnect as Chief Executive Officer and Chairman of the Board.

About Summit Interconnect: Summit Interconnect is the largest, privately held PCB manufacturer in North America. The company is focused on the fast-growing defense and high-performance commercial sectors in the North American market. Summit offers solutions ranging from advanced cutting-edge prototyping to complex high-mix, low-to-mid volume production. Summit's seven manufacturing facilities are located across California, Illinois, Colorado, and Toronto, Canada. For more information, please visit summitinterconnect.com.

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